Silicon P-Channel MOS FET

HITACHI

I. Com.cn

ADE-208-381 1st. Edition

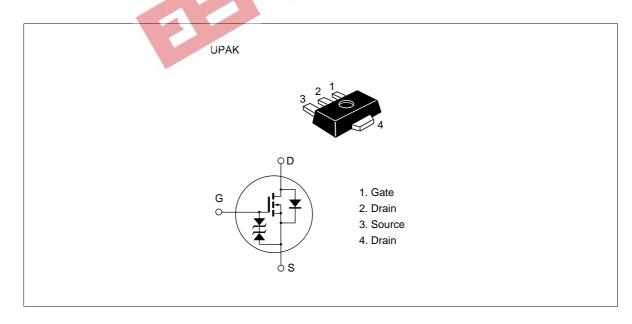
Application

High speed power switching

Features

- Low on-resistance.
- Low drive power
- High speed switching
- 2.5 V gate drive device.

Outline





Absolute Maximum Ratings (Ta = 25°C)

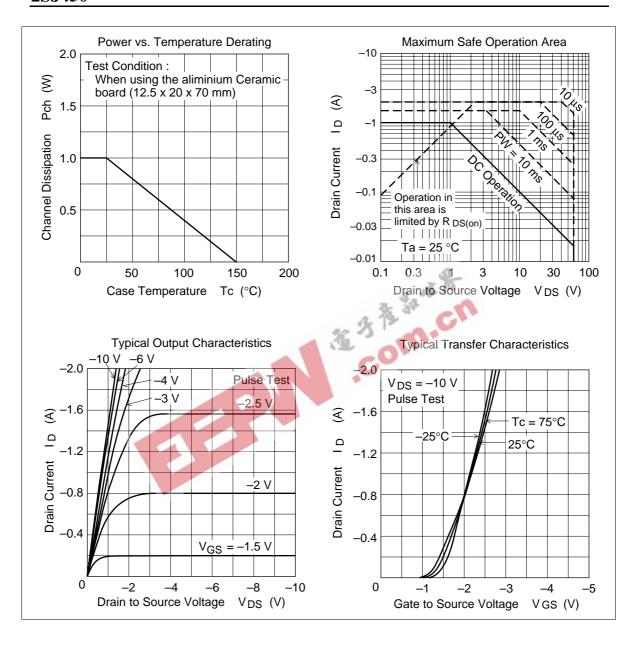
Item	Symbol	Ratings	Unit				
Drain to source voltage	V _{DSS}	-60	V				
Gate to source voltage	V _{GSS}	±20	V				
Drain current	I _D	-1	A				
Drain peak current	L _{D(pulse)} *1	-2	A				
Drain peak current	I _{DR}	–1	Α				
Channel dissipation	Pch*2	1	W				
Channel temperature	Tch	150	°C				
Storage temperature	Tstg	-55 to +150	°C				
Notes: 1. PW ≤ 100 μs, duty cycle ≤ 10% 2. When using aluminium ceramic board (12.5 × 20 × 70 mm)							

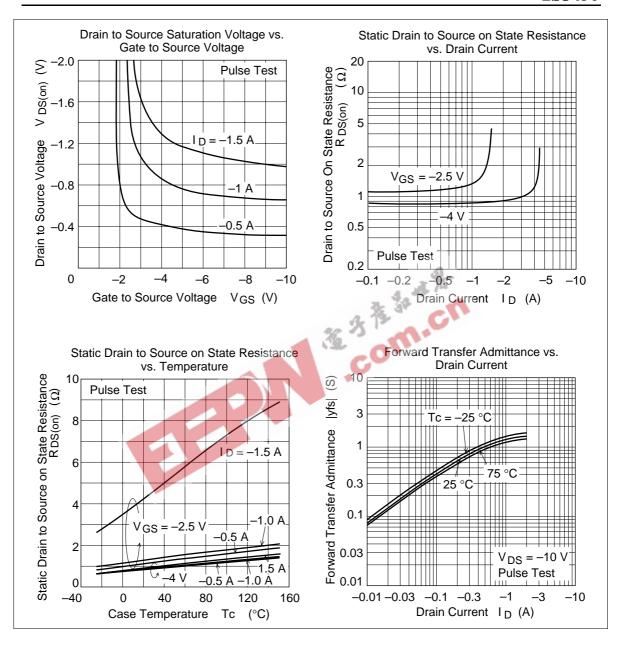


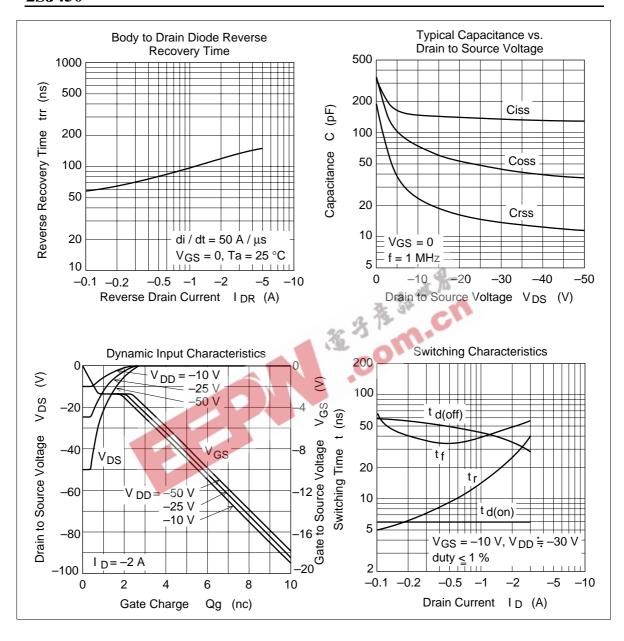
Electrical Characteristics ($Ta = 25^{\circ}C$)

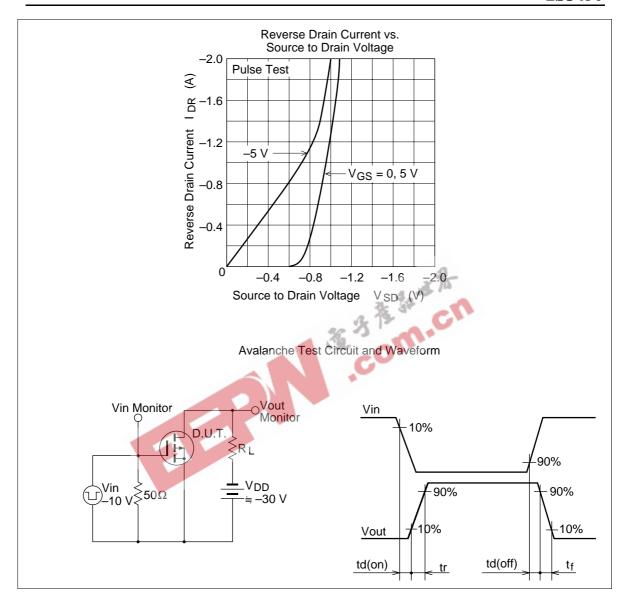
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	-60	_	_	V	$I_{D} = -10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	- 50	μΑ	$V_{DS} = -50 \text{ V}, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-0.5	_	-1.5	V	$V_{DS} = -10 \text{ V}, I_{D} = -1 \text{ mA}$
Static drain to source on state resistance	R _{DS(on)}	_	0.85	1.2	Ω	$I_D = -0.5 \text{ A}$ $V_{GS} = -4 \text{ V}^{*1}$
Static drain to source on state resistance	R _{DS(on)}	_	1.1	1.9	Ω	$I_D = -0.3 \text{ A}$ $V_{GS} = -2.5 \text{ V}^{*1}$
Fowerd transfer admittance	y _{fs}	0.6	1.0	九為	S	$I_{D} = -0.5 \text{ A}$ $V_{DS} = -10 \text{ V}$
Input capacitance	Ciss	_	150	2)	pF	V _{DS} = -10 V
Output capacitance	Coss	-	72	~0.0	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	7 ,	24	1	pF	f = 1 MHz
Turn-on delay time	t _{d(on)}	-)\	6	_	ns	$V_{GS} = -10 \text{ V}, I_{D} = -0.5 \text{ A}$
Rise time	t _r		9	_	ns	$R_L = 60 \Omega$
Turn-off delay time	t _{d(off)}	_	50	_	ns	_
Fall time	t _f	_	35	_	ns	_
Body to drain diode forward voltage	V_{DF}	_	-0.9	_	V	$I_F = -1 A, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	_	100	_	ns	$I_F = -1 A$, $V_{GS} = 0$ diF/dt = 50A/ μ s

Note: 1. Pulse Test Marking is "UY".



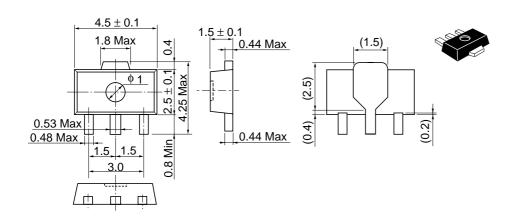








Unit: mm



Hitachi Code	UPAK
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.050 g

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